

ForTii® LDS85B

PPA-GF30

30% Glass Reinforced, PA4T, Laser Direct Structuring (LDS)

ForTii® LDS85B enables mechanical function integration with high impact resistance and ductility. LDS85B has very good plating performance.

Properties	Typical Data	Unit	Test Method
Rheological properties			
	dry / cond		
Molding shrinkage (parallel)	0.33 / *	%	ISO 294-4
Molding shrinkage (normal)	1.3 / *	%	ISO 294-4
Mechanical properties			
	dry / cond		
Tensile modulus	10000 / 10000	MPa	ISO 527-1/-2
Tensile modulus (120°C)	5600 / -	MPa	ISO 527-1/-2
Tensile modulus (160°C)	3000	MPa	ISO 527-1/-2
Stress at break	125 / 105	MPa	ISO 527-1/-2
Stress at break (120°C)	64 / -	MPa	ISO 527-1/-2
Stress at break (160°C)	45	MPa	ISO 527-1/-2
Strain at break	2.1 / 2.1	%	ISO 527-1/-2
Strain at break (120°C)	4 / -	%	ISO 527-1/-2
Strain at break (160°C)	6	%	ISO 527-1/-2
Flexural modulus	9400 / 9600	MPa	ISO 178
Flexural strength	185 / 165	MPa	ISO 178
Flexural modulus (120°C)	5400	MPa	ISO 178
Flexural modulus (160°C)	3100	MPa	ISO 178
Charpy impact strength (+23°C)	35 / 35	kJ/m ²	ISO 179/1eU
Charpy notched impact strength (+23°C)	4 / 3.6	kJ/m ²	ISO 179/1eA



Property Data

ForTii[®] LDS85B

Properties	Typical Data	Unit	Test Method
Thermal properties			
Melting temperature (10°C/min)	325 / *	°C	ISO 11357-1/-3
Temp. of deflection under load (1.80 MPa)	285 / *	°C	ISO 75-1/-2
Coeff. of linear therm. expansion (parallel)	0.18 / *	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (normal)	0.6 / *	E-4/°C	ISO 11359-1/-2
Burning Behav. at 3.0 mm nom. thickn.	HB / *	class	IEC 60695-11-10
Thickness tested	3 / *	mm	IEC 60695-11-10
UL recognition	Yes / *	-	-
Electrical properties			
Relative permittivity (1GHz)	3.78 / 3.85	-	IEC 60250
Other properties			
Humidity absorption	1.4 / *	%	Sim. to ISO 62
Density	1510 / -	kg/m ³	ISO 1183

